

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT6146328

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TING-YING WU	05/23/2019
CHIEN-HSIANG HUANG	05/23/2019
CHIN-YUAN LO	05/23/2019
CHIH-WEI CHANG	05/23/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	REALTEK SEMICONDUCTOR CORP.
<b>Street Address:</b>	NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK,
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16897424
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)574-5876
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<b>ATTORNEY DOCKET NUMBER:</b>	107P001981US
<b>NAME OF SUBMITTER:</b>	ZHUO XU
<b>SIGNATURE:</b>	/ZHUO XU/
<b>DATE SIGNED:</b>	06/10/2020
<b>Total Attachments: 3</b>	
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source=107P001981US-ASSIGNMENT#page2.tif	



**ASSIGNMENT DEED**

Attorney docket No. 107P001981US

This Assignment agreement is applicable to an invention entitled (invention Title):  
ELECTRONIC PACKAGE STRUCTURE AND CHIP THEREOF

The PATENT RIGHTS referred to in this agreement are:

(Check one)

- a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignment
- U.S. Patent Application Serial No. \_\_\_\_\_, filed \_\_\_\_\_
- U.S. Patent No. \_\_\_\_\_, issued \_\_\_\_\_

The PATENT RIGHTS assigned under this agreement are:

(Check One)

- U.S. Patent rights only
- worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. Patent Application identified above.

I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.

The above-identified Application was made or authorized by me/us.

I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

The ASSIGNOR(S) referred to in this agreement is (or are):

(Full name of sole or first assignor) TING-YING WU (FAMILY NAME: WU)  
(Address) NO.371, XUEFU E. RD., ZHUDONG TOWNSHIP, HSINCHU COUNTY 310, TAIWAN, R.O.C.

(Full name of second joint assignor, if any) CHIEN-HSIANG HUANG (FAMILY NAME:HUANG)  
(Address) 5F., NO.126, SHENGLI 6TH ST., ZHUBEI CITY, HSINCHU COUNTY 302, TAIWAN, R.O.C.

(Full name of third joint assignor, if any) CHIN-YUAN LO (FAMILY NAME: LO)  
(Address) 1F., NO.57, ZHENXING RD., EAST DIST., HSINCHU CITY 300, TAIWAN, R.O.C.

(Full name of fourth joint assignor, if any) CHIH-WEI CHANG (FAMILY NAME:CHANG)  
(Address) NO.35, LN. 777, SEC. LITOUZHAN, WENSHAN RD., XINPU TOWNSHIP, HSINCHU COUNTY 305,TAIWAN, R.O.C.

(Full name of fifth joint assignor, if any) \_\_\_\_\_  
(Address) \_\_\_\_\_

(Full name of sixth joint assignor, if any) \_\_\_\_\_  
(Address) \_\_\_\_\_

Additional assignors are being named on separately numbered sheets attached hereto.

The sole or first ASSIGNEE(S) referred to in this agreement is (or are):

(Name of Assignee) REALTEK SEMICONDUCTOR CORP.

(Address of Assignee) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300,  
TAIWAN, R.O.C.

The sole or first ASSIGNEE is: (Check One)

an individual

a partnership

a Corporation of TAIWAN, R.O.C. (State or Country)

The second ASSIGNEE(S) (if any) referred to in this agreement is (or are):

(Name of Assignee) \_\_\_\_\_

(Address of Assignee) \_\_\_\_\_

The second ASSIGNEE is: (Check One)

an individual

a partnership

a Corporation of \_\_\_\_\_ ( (State or Country)

The third ASSIGNEE(S) (if any) referred to in this agreement is (or are):

(Name of Assignee) \_\_\_\_\_

(Address of Assignee) \_\_\_\_\_

The second ASSIGNEE is: (Check One)

an individual

a partnership

a Corporation of \_\_\_\_\_ ( (State or Country)

Additional assignees are being named on separately numbered sheets attached hereto

The ASSIGNOR(S), in consideration of \$1.00 paid by each ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE; their successors and assigns:

the full and exclusive right to the invention;

an equal interest in and to the entire right, title and interest in and to the PATENT RIGHTS in the invention, all continuations, continuations-in-part, divisionals, re-issues, and re-examination patents and patent applications; and

the right to claim priority under 35 U.S.C. § 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(S) as the ASSIGNEE(S) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(S), their successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE(S), or their representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(S), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(S), their successors and assigns, to obtain and enforced proper protection for said invention.

I/WE hereby give our Attorney authorization to insert the Serial Number and filing date of the above-referenced Patent Application when known.

TING-YING WU (FAMILY NAME: WU)

Ting Ying Wu  
(Signature of sole or first assignor)

2019.5.23  
(Date)

CHIEN-HSIANG HUANG (FAMILY NAME:HUANG)

Chien-Hsiang Huang  
(Signature of second assignor, if any)

2019.5.23  
(Date)

CHIN-YUAN LO (FAMILY NAME: LO)

CHIN-YUAN LO  
(Signature of third assignor, if any)

2019.5.23  
(Date)

CHIH-WEI CHANG (FAMILY NAME:CHANG)

Chih wei Chang  
(Signature of fourth assignor, if any)

2019/5/23  
(Date)

\_\_\_\_\_  
(Signature of fifth assignor, if any)

\_\_\_\_\_  
(Date)

\_\_\_\_\_  
(Signature of sixth assignor, if any)

\_\_\_\_\_  
(Date)